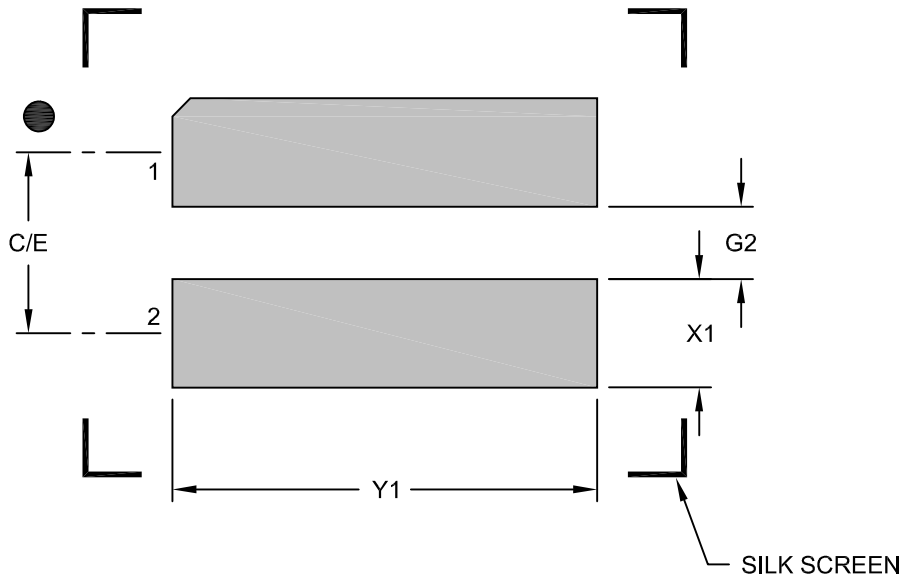


2-Pad Extra-Thin Single Flat, No Lead Package (QJB) - 5x3.5x0.4 mm Body [XSFN] Atmel Legacy GPC YDR

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	2.00 BSC		
Contact Pad Spacing	C		2.00	
Contact Pad Width (Xnn)	X1			1.20
Contact Pad Length (Xnn)	Y1			4.70
Contact Pad to Contact Pad (Xnn)	G2	0.80		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process